

Dear Customer,

With this INFINEON Technologies Information Note we would like to inform you about the following

Capacity expansion by implementation of 300mm wafer diameter for Gen 10.2 and Gen 12.7 for TO220 package in addition to qualified site Great Team Backend Foundry (Dongguan), Ltd., China

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► **Products affected:** Please refer to 1_cip16617a

► **Detailed Change Information:**

Subject: Capacity expansion by implementation of 300mm wafer diameter for Gen 10.2 and Gen 12.7 for TO220 package on addition to qualified site Great Team Backend Foundry (Dongguan), Ltd., China

Reason: Infineon has successfully qualified our already well established BE locations GTBF, ASE-WH, and PSIL to handle incoming 300mm Si. This will improve the supply performance for our customers.

Description:

■ **SETO220 Back End Location**

Old

- Great Team Backend Foundry (Dongguan), Ltd., China

New

- Great Team Backend Foundry (Dongguan, Ltd., China
- ASE (Weihai) Inc., China
- PSI, Philippines

► **Product Identification:** Wafer fab origins will not be distinguished through the external part marking or shipping labels, however, based on the assembly lot code and marked on the device. IFX internal systems will be able to trace the site of the wafer lots used to produce the final product.

► **Impact of Change:** No change in form, fit and function.

► **Attachments:** 1_cip16617a List of affected products

► **Intended start of delivery:** 2018-01-15

If you have any questions, please do not hesitate to contact your local Sales office.